



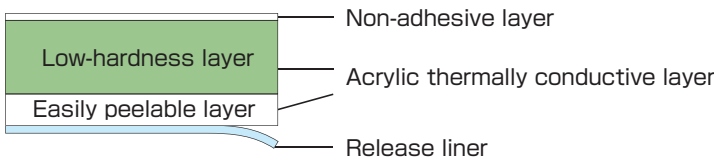
COOLPROVIDE™ / CPVP-30-F



Silicone free, low-hardness, high-thermally conductive pad (3W/m · K)

- The two-layer structured putty can be handled in the same way as a pad.
- has a thermal conductivity of 3.0W/m · K, which is 2.1 times higher than the existing product.
- Silicon free COOLPROVIDE contains no siloxane.
- With excellent flexibility and stress relaxation, the assembled pad can lower the load on heating elements and PCBs.
- Recommended operating temperature: -40-125°C
- bleeds less oil compared with the silicone type.

Cross-section view

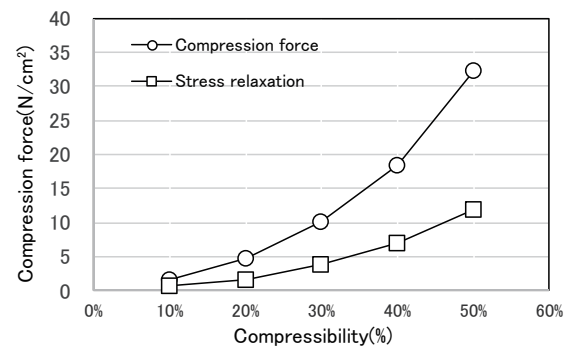


Properties

Item	Unit	Compliance standard	CPVP-30-F
Thickness	mm	—	1.0/1.5/2.0*1, 3.0/4.0
Thermal conductivity	W/m · K	ISO 22007-2 (Hot Disc method)	3.0 (Low-hardness layer)
Hardness	ASKER C	JIS K 7312	7 (Low-hardness layer)
	Shore OO	ASTM D 2240	18 (Low-hardness layer)
Volume resistivity	Ω · cm	JIS K 6911	1.0 × 10 ¹¹
Flammability	—	UL94	Equivalent to V-0
Color	—	—	Green/White
Recommended operating temperature	°C	—	-40~125

※ 1.0, 1.5 and 2.0mm thick products are under development.

Compressive stress relaxation properties



Sample dimensions : □ 10mm(t=4.0mm)
 Cross-head speed : 1mm/min
 Compression plate materials

Upper : Stainless steel Φ28mm
 Lower : Gold plated copper Φ106mm

※ Compressive force is the largest load value immediately after compression.

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